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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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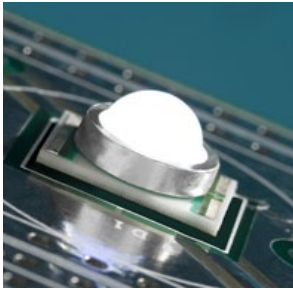
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# Cree® XLamp® XR-E LED



## PRODUCT DESCRIPTION

The XLamp® XR-E LED is leading the LED lighting revolution with its unprecedented lighting-class brightness, efficacy, lifetime and quality of light. These lighting-class features enable the XLamp XR-E LED to replace many traditional light sources and save money with energy-efficient light and long lifetimes.

Cree XLamp LEDs bring high performance and quality of light to a wide range of lighting applications, including color-changing lighting, portable and personal lighting, outdoor lighting, indoor directional lighting, commercial lighting and emergency-vehicle lighting.

## FEATURES

- Available in white (2600 K to 10,000 K CCT), blue, royal blue and green
- Maximum drive current: up to 1000 mA
- Maximum junction temperature: 150 °C
- Industry-leading JEDEC standard pre-qualification testing
- Reflow solderable – JEDEC J-STD-020C compatible
- Electrically neutral thermal path
- RoHS and REACH compliant
- UL® recognized component (E349212)



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## CHARACTERISTICS

Characteristics	Unit	Minimum	Typical	Maximum
Thermal Resistance, junction to solder point	°C/W		8	
Viewing Angle (FWHM) - white	degrees		90	
Viewing Angle (FWHM) - royal blue, blue, green	degrees		100	
Temperature Coefficient of Voltage - white, royal blue, blue, green	mV/°C		-4.0	
ESD Classification (HBM per Mil-Std-883D)			Class 2	
DC Forward Current - white ≥ 5000 K, royal blue, blue	mA			1000
DC Forward Current - white < 5000 K, green	mA			700
DC Pulse Current (@ 1 kHz, 10% duty cycle)	A			1.8
Reverse Voltage	V			5
Forward Voltage (@ 350 mA)	V		3.3	3.9
Forward Voltage (@ 700 mA)	V		3.5	
Forward Voltage (@ 1000 mA) - white ≥ 5000 K, royal blue, blue	V		3.7	
LED Junction Temperature	°C			150

## FLUX CHARACTERISTICS - WHITE ( $T_j = 25\text{ °C}$ )

The following tables describe the available colors and flux for XR-E LEDs by listing the correlated color temperature or dominant wavelength range for the entire family and by providing several base order codes. It is important to note that the base order codes listed here are a subset of the total available order codes for the product family. For more order codes, as well as a complete description of the order-code nomenclature, please consult the XR Family Binning and Labeling document.

Color	CCT Range		Minimum Luminous Flux		Order Code
	Minimum	Maximum	Group	Flux (lm)	
Cool White	5000 K	10,000 K	P4	80.6	XREWHT-L1-0000-00901
			Q2	87.4	XREWHT-L1-0000-00A01
			Q3	93.9	XREWHT-L1-0000-00B01
			Q4	100	XREWHT-L1-0000-00C01
			Q5	107	XREWHT-L1-0000-00D01
			R2	114	XREWHT-L1-0000-00E01
Neutral White	3700 K	5000 K	P3	73.9	XREWHT-L1-0000-008E4
			P4	80.6	XREWHT-L1-0000-009E4
			Q2	87.4	XREWHT-L1-0000-00AE4
			Q3	93.9	XREWHT-L1-0000-00BE4
			Q4	100	XREWHT-L1-0000-00CE4
Warm White	2600 K	3700 K	N3	56.8	XREWHT-L1-0000-005E7
			N4	62.0	XREWHT-L1-0000-006E7
			P2	67.2	XREWHT-L1-0000-007E7
			P3	73.9	XREWHT-L1-0000-008E7
			P4	80.6	XREWHT-L1-0000-009E7

### Notes:

- Cree maintains a tolerance of  $\pm 7\%$  on flux and power measurements,  $\pm 0.005$  on chromaticity (CCx, CCy) measurements and  $\pm 2$  on CRI measurements. See the Measurements section (page 10).
- Typical CRI for Cool White & Neutral White (3700 K – 10,000 K CCT) is 75.
- Typical CRI for Warm White (2600 K – 3700 K CCT) is 80.

**FLUX CHARACTERISTICS - COLOR (T<sub>J</sub> = 25 °C)**

The following tables describe the available colors and flux for XR-E LEDs by listing the correlated color temperature or dominant wavelength range for the entire family and by providing several base order codes. It is important to note that the base order codes listed here are a subset of the total available order codes for the product family. For more order codes, as well as a complete description of the order-code nomenclature, please consult the XR Family Binning and Labeling document.

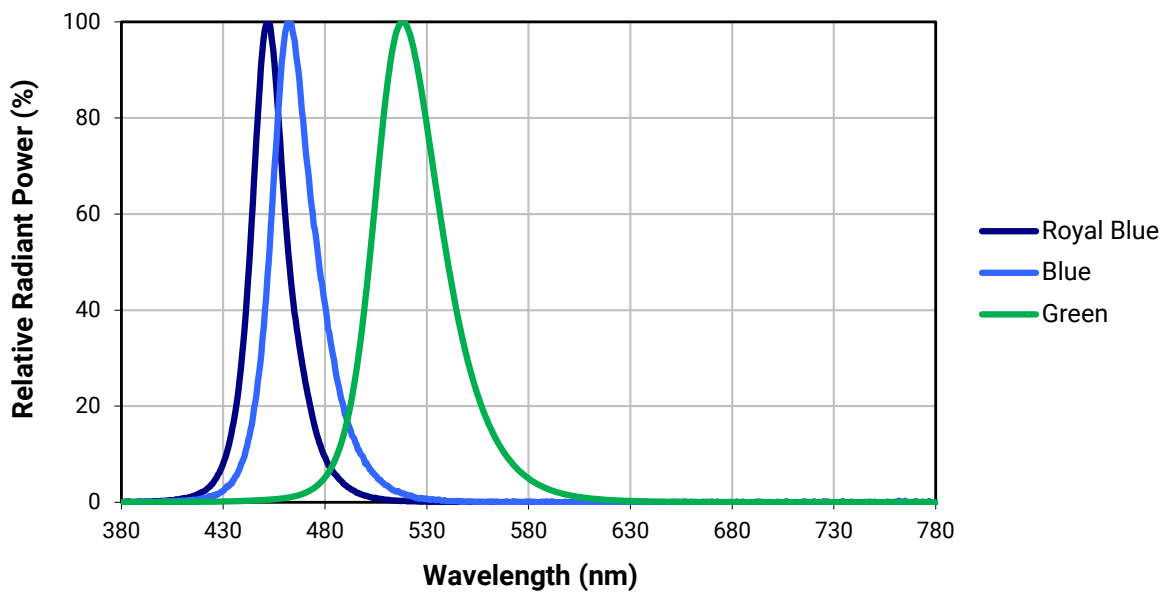
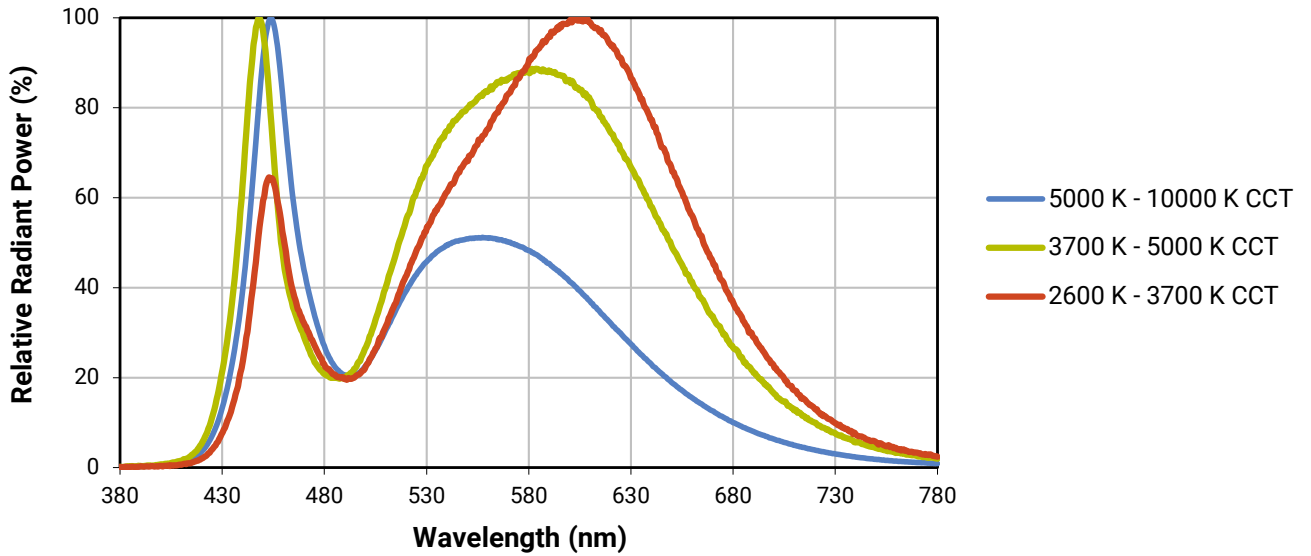
Color	Dominant Wavelength Range				Minimum Radiant Flux (mW)		Order Code
	Minimum		Maximum		Group	Flux (mW)	
	Group	DWL (nm)	Group	DWL (nm)			
Royal Blue	D3	450	D5	465	13	300	XREROY-L1-0000-00801
					14	350	XREROY-L1-0000-00901
					15	425	XREROY-L1-0000-00A01

Color	Dominant Wavelength Range				Minimum Luminous Flux (lm)		Order Code
	Minimum		Maximum		Group	Flux (lm)	
	Group	DWL (nm)	Group	DWL (nm)			
Blue	B3	465	B6	485	J	23.5	XREBLU-L1-0000-00J01
					K	30.6	XREBLU-L1-0000-00K01

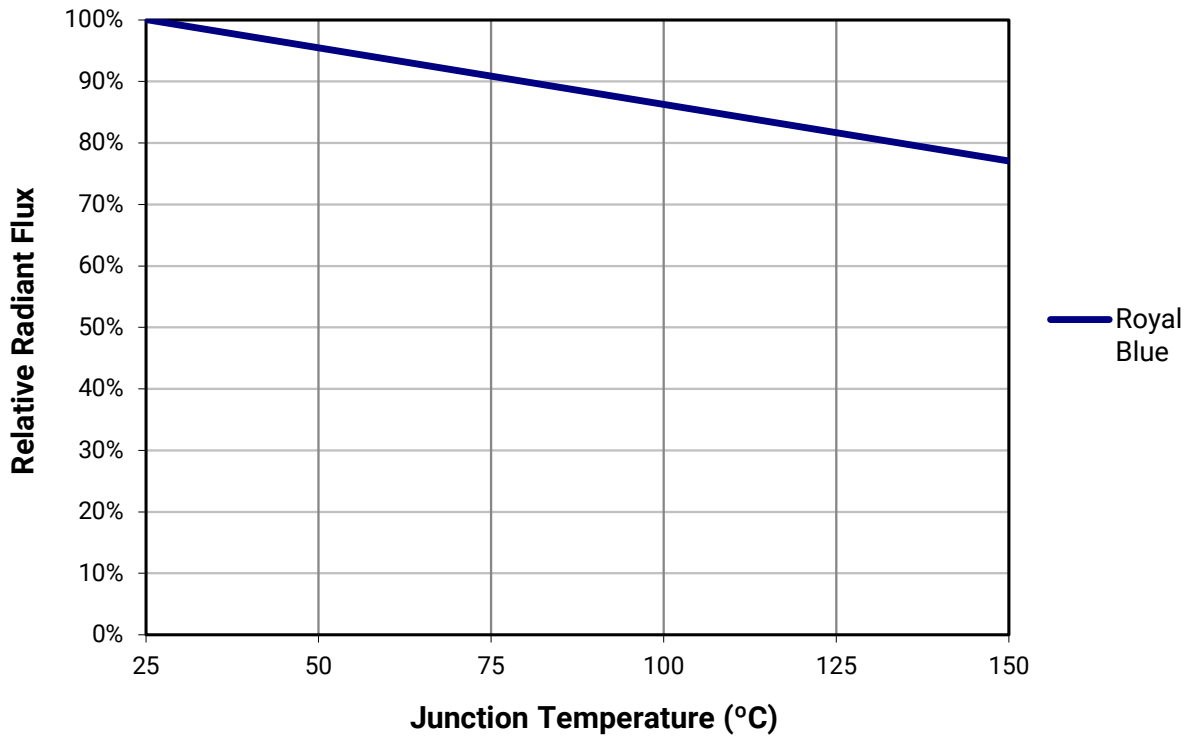
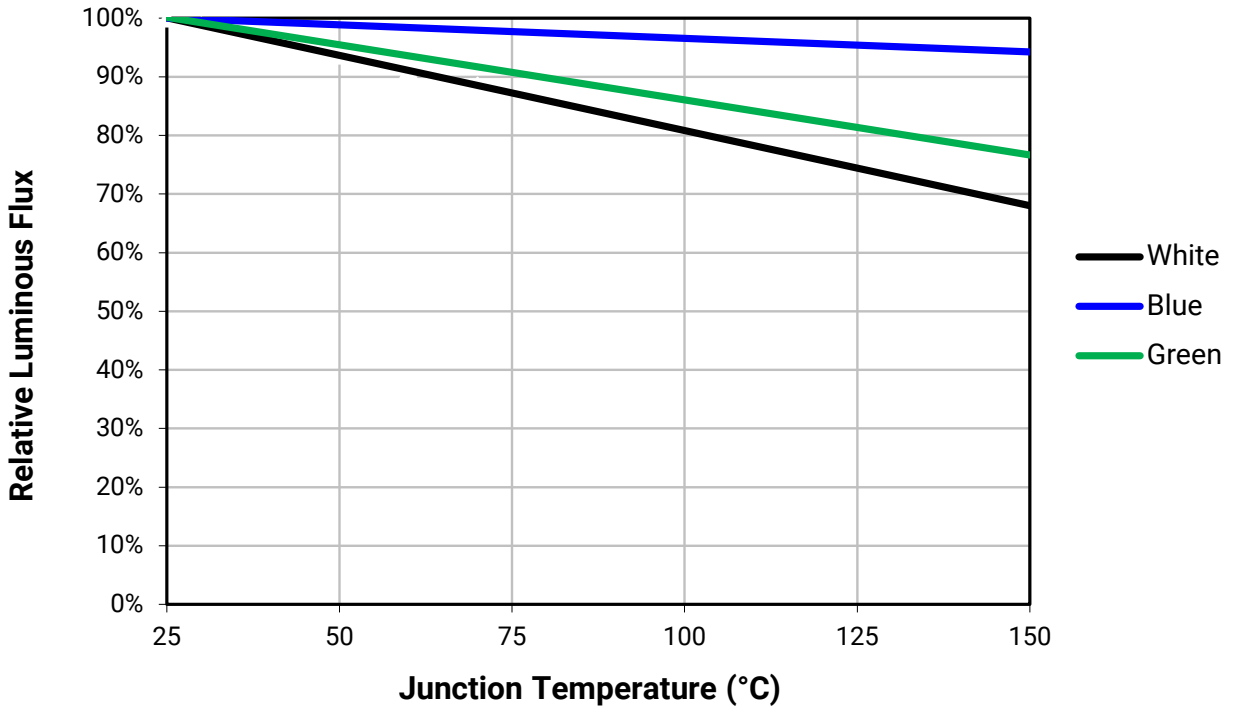
Color	Dominant Wavelength Range				Minimum Luminous Flux (lm)		Order Code
	Minimum		Maximum		Group	Flux (lm)	
	Group	DWL (nm)	Group	DWL (nm)			
Green	G2	520	G4	535	P	67.2	XREGRN-L1-0000-00P01

Note: Cree maintains a tolerance of ±7% on flux and power measurements and ±1 nm on dominant wavelength measurements. See the Measurements section (page 10).

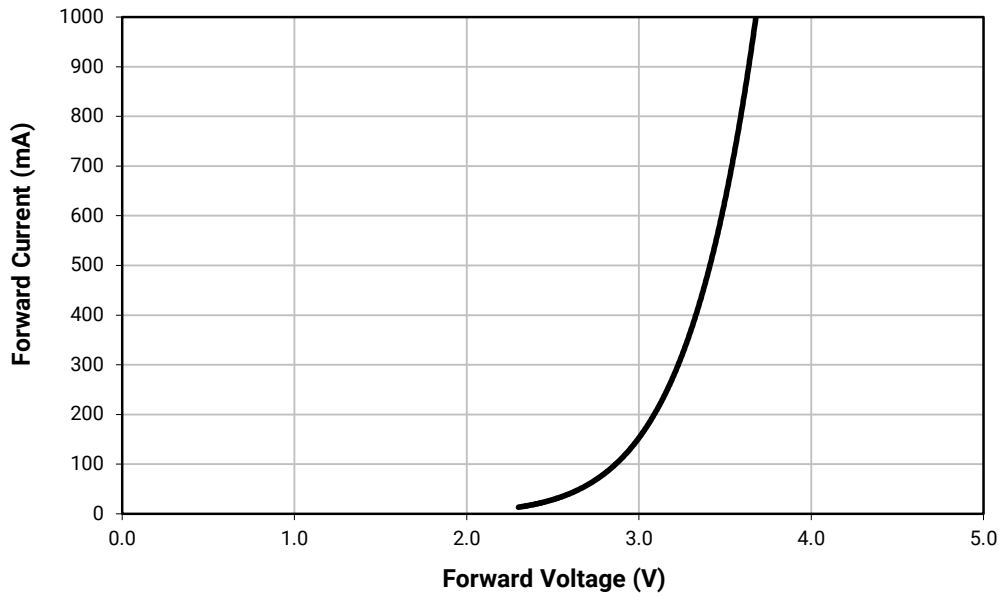
**RELATIVE SPECTRAL POWER DISTRIBUTION**



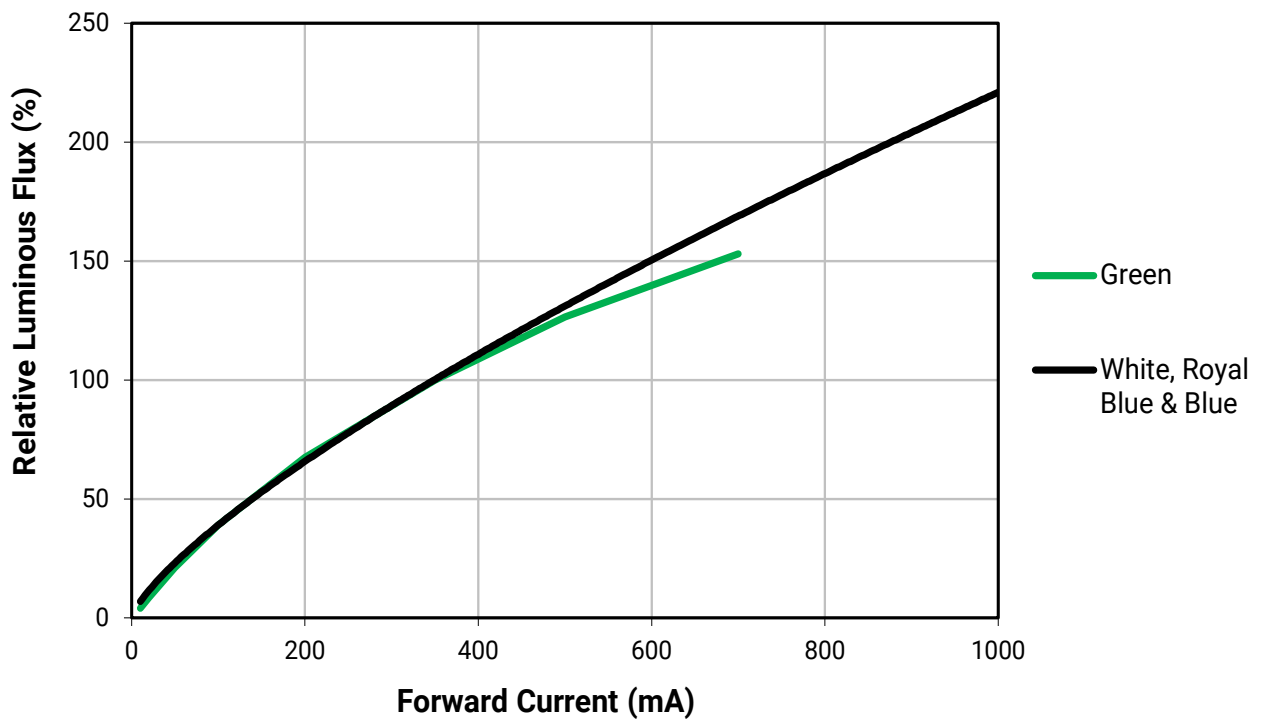
**RELATIVE FLUX VS. JUNCTION TEMPERATURE ( $I_F = 350$  mA)**



**ELECTRICAL CHARACTERISTICS ( $T_j = 25\text{ }^\circ\text{C}$ )**

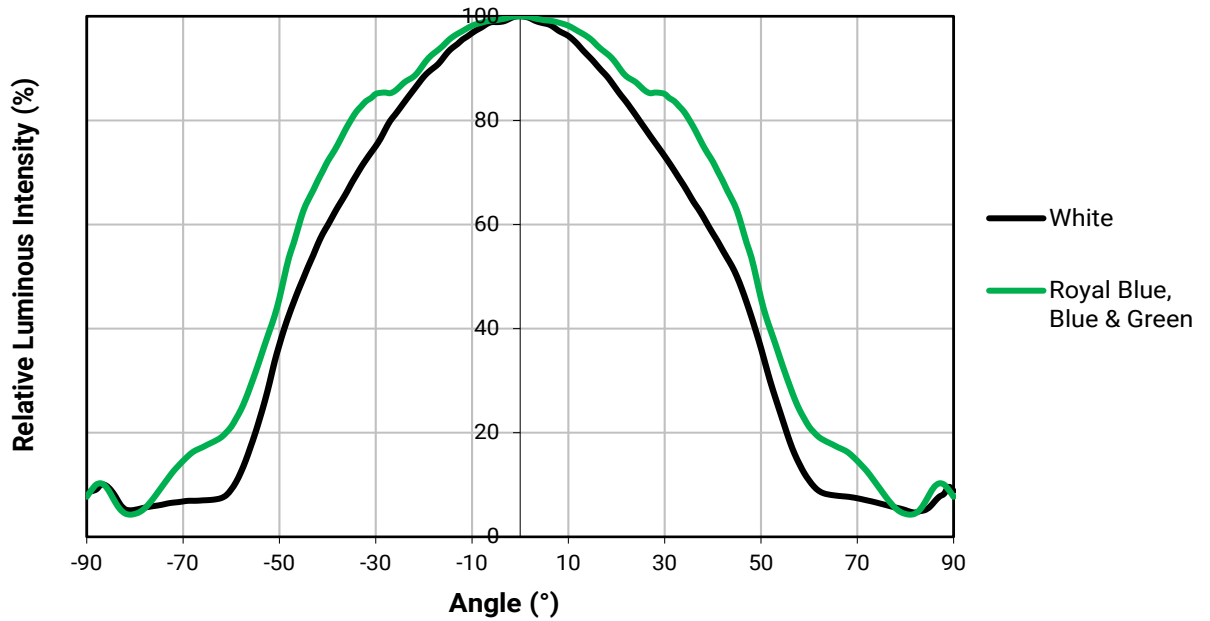


**RELATIVE FLUX VS. CURRENT ( $T_j = 25\text{ }^\circ\text{C}$ )**

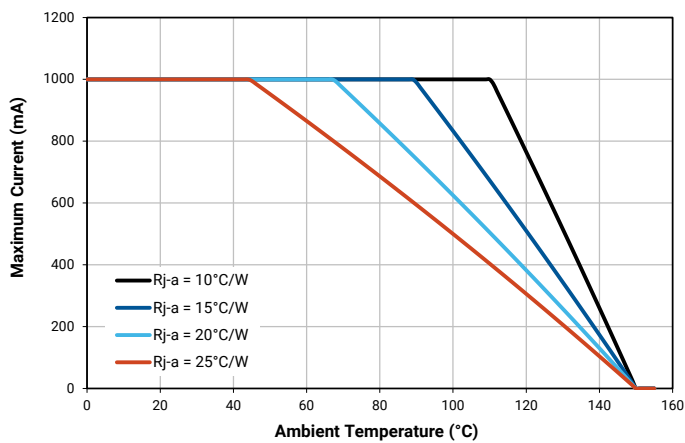




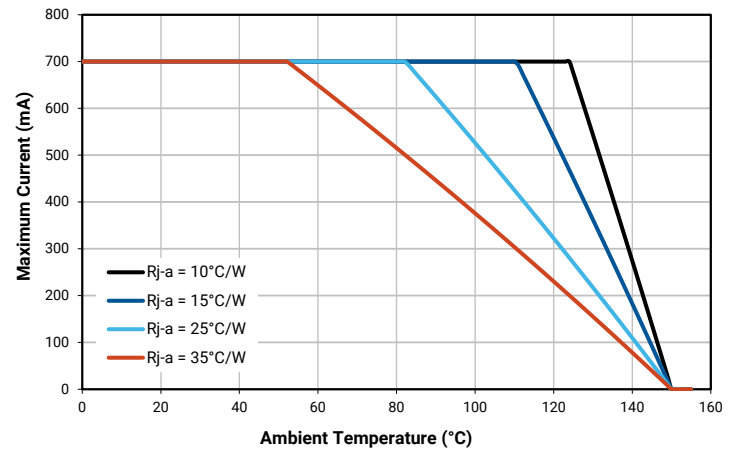
**TYPICAL SPATIAL DISTRIBUTION**



**THERMAL DESIGN**



**White ≥ 5,000 K, Royal Blue, Blue**

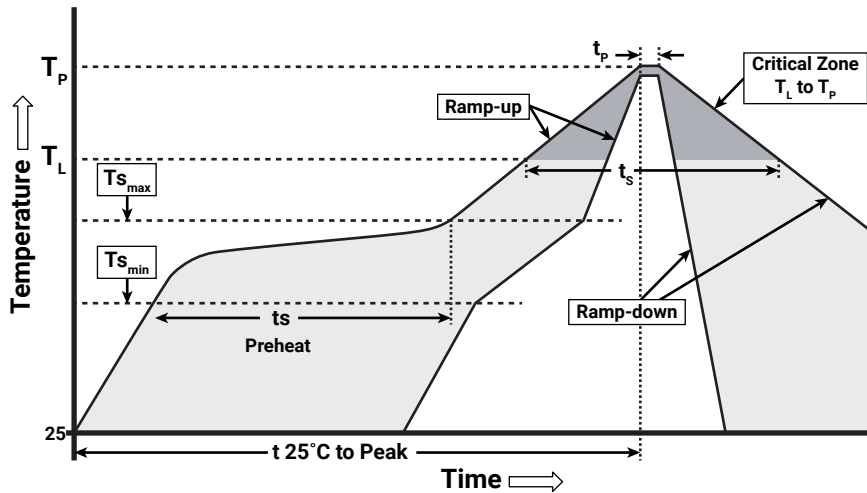


**White < 5,000 K, Green**

**REFLOW SOLDERING CHARACTERISTICS**

In testing, Cree has found XLamp XR-E LEDs to be compatible with JEDEC J-STD-020C, using the parameters listed below. As a general guideline, Cree recommends that users follow the recommended soldering profile provided by the manufacturer of the solder paste used.

Note that this general guideline may not apply to all PCB designs and configurations of reflow soldering equipment.



IPC/JEDEC J-STD-020C

Profile Feature	Lead-Free Solder
Average Ramp-Up Rate ( $T_{s_{max}}$ to $T_P$ )	1.2 °C/second
Preheat: Temperature Min ( $T_{s_{min}}$ )	120 °C
Preheat: Temperature Max ( $T_{s_{max}}$ )	170 °C
Preheat: Time ( $t_{s_{min}}$ to $t_{s_{max}}$ )	65-150 seconds
Time Maintained Above: Temperature ( $T_L$ )	217 °C
Time Maintained Above: Time ( $t_l$ )	45-90 seconds
Peak/Classification Temperature ( $T_P$ )	235 - 245 °C
Time Within 5 °C of Actual Peak Temperature ( $t_p$ )	20-40 seconds
Ramp-Down Rate	1 - 6 °C/second
Time 25 °C to Peak Temperature	4 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface.

**NOTES**

**Measurements**

The luminous flux, radiant power, chromaticity, forward voltage and CRI measurements in this document are binning specifications only and solely represent product measurements as of the date of shipment. These measurements will change over time based on a number of factors that are not within Cree’s control and are not intended or provided as operational specifications for the products. Calculated values are provided for informational purposes only and are not intended as specifications.

**Pre-Release Qualification Testing**

Please read the [LED Reliability Overview](#) for details of the qualification process Cree applies to ensure long-term reliability for XLamp LEDs and details of Cree’s pre-release qualification testing for XLamp LEDs.

**Lumen Maintenance**

Cree now uses standardized IES LM-80-08 and TM-21-11 methods for collecting long-term data and extrapolating LED lumen maintenance. For information on the specific LM-80 data sets available for this LED, refer to the public [LM-80 results document](#).

Please read the [Long-Term Lumen Maintenance application note](#) for more details on Cree’s lumen maintenance testing and forecasting. Please read the [Thermal Management application note](#) for details on how thermal design, ambient temperature, and drive current affect the LED junction temperature.

**Moisture Sensitivity**

Cree recommends keeping XLamp XR-E LEDs in the provided, resealable moisture-barrier packaging (MBP) until immediately prior to soldering. Unopened MBPs that contain XLamp LEDs do not need special storage for moisture sensitivity.

Once the MBP is opened, XLamp XR-E LEDs should be handled and stored as MSL 4 per JEDEC J-STD-033, meaning they have limited exposure time before damage to the LED may occur during the soldering operation. The table on the right specifies the maximum exposure time in days depending on temperature and humidity conditions. LEDs with exposure time longer than the specified maximums must be baked according to the baking conditions listed below.

Temp.	Maximum Percent Relative Humidity						
	30%	40%	50%	60%	70%	80%	90%
30 °C	9	5	4	3	1	1	1
25 °C	12	7	5	4	2	1	1
20 °C	17	9	7	6	2	2	1

**Baking Conditions**

It is not necessary to bake all XLamp LEDs. Only the LEDs that meet all of the following criteria must be baked:

1. LEDs that have been removed from the original MBP.
2. LEDs that have been exposed to a humid environment longer than listed in the Moisture Sensitivity section above.
3. LEDs that have not been soldered.

LEDs should be baked at 80 °C for 24 hours. LEDs may be baked on the original reels. Remove LEDs from the MBP before baking. Do not bake parts at temperatures higher than 80 °C. This baking operation resets the exposure time as defined in the Moisture Sensitivity section above.

## NOTES - CONTINUED

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### Storage Conditions

XLamp LEDs that have been removed from the original MBP but not soldered yet should be stored in a room or cabinet that will maintain an atmosphere of  $25 \pm 5$  °C and no greater than 10% RH (relative humidity). For LEDs stored in these conditions, storage time does not add to exposure time as defined in the Moisture Sensitivity section above.

### RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of [www.cree.com](http://www.cree.com).

### REACH Compliance

REACH substances of very high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.

### UL® Recognized Component

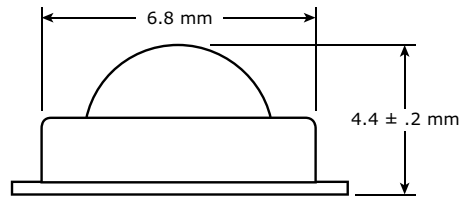
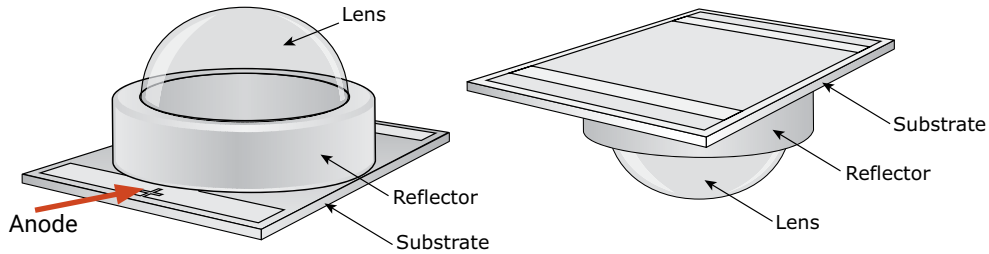
Level 4 enclosure consideration. The LED package or a portion thereof has been investigated as a fire and electrical enclosure per ANSI/UL 8750.

### Vision Advisory

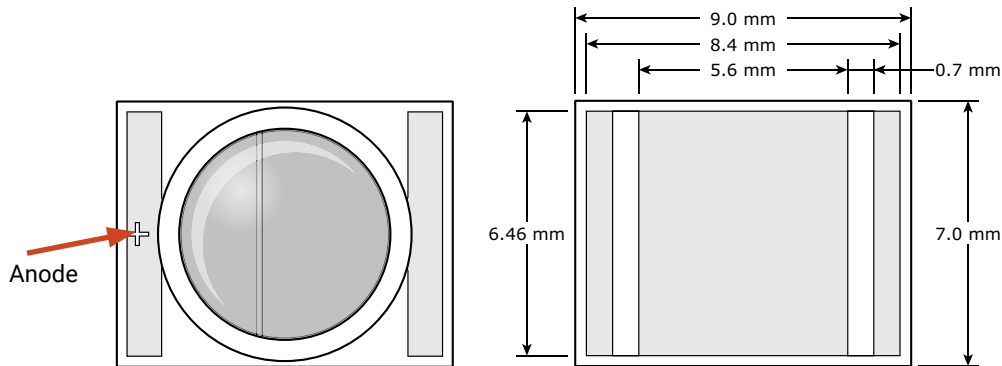
**WARNING:** Do not look at an exposed lamp in operation. Eye injury can result. For more information about LEDs and eye safety, please refer to the [LED Eye Safety application note](#).

**MECHANICAL DIMENSIONS (T<sub>A</sub> = 25 °C)**

All measurements are ±.1 mm unless otherwise indicated.

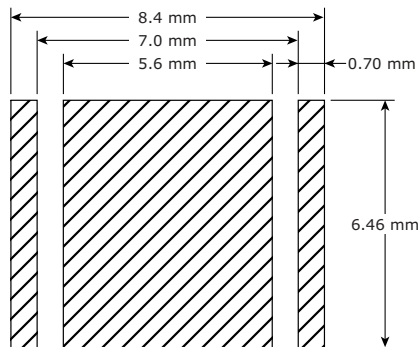


Side View

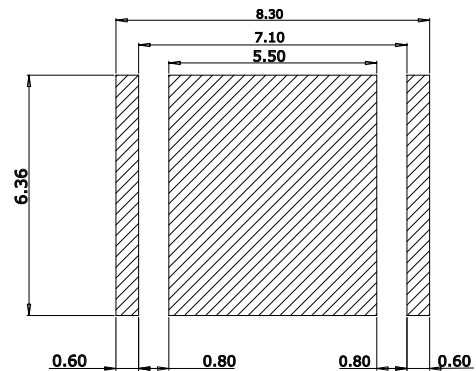


Top View

Bottom View



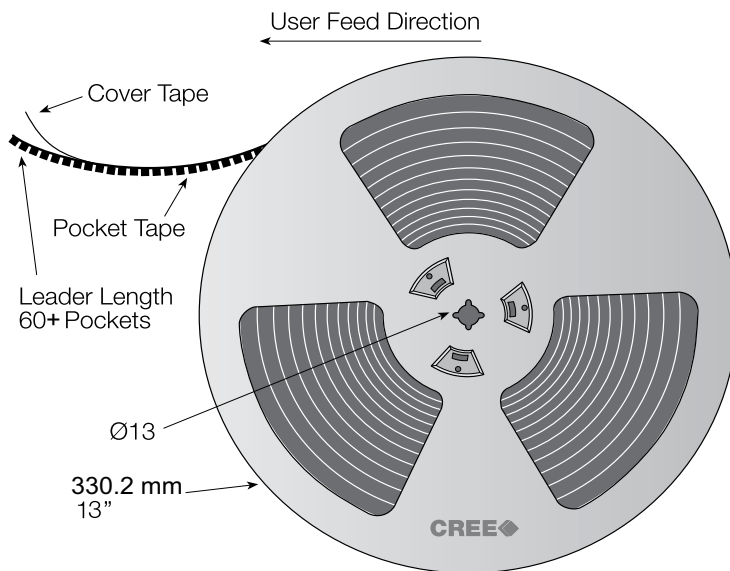
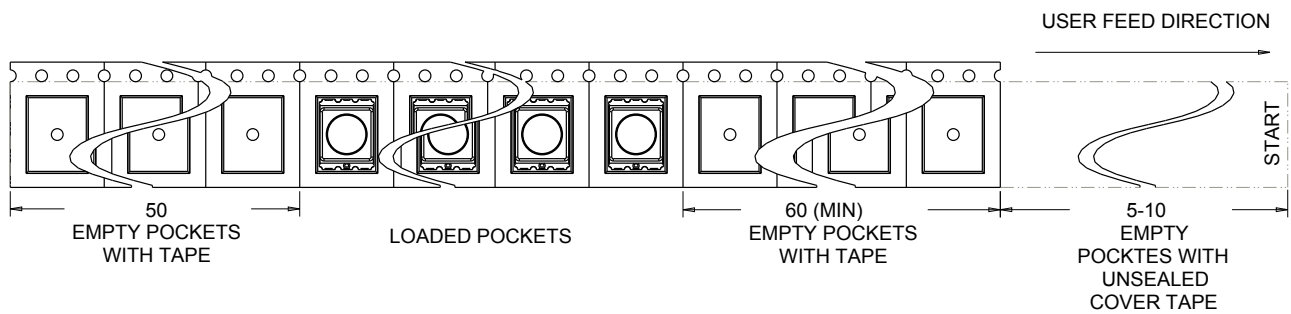
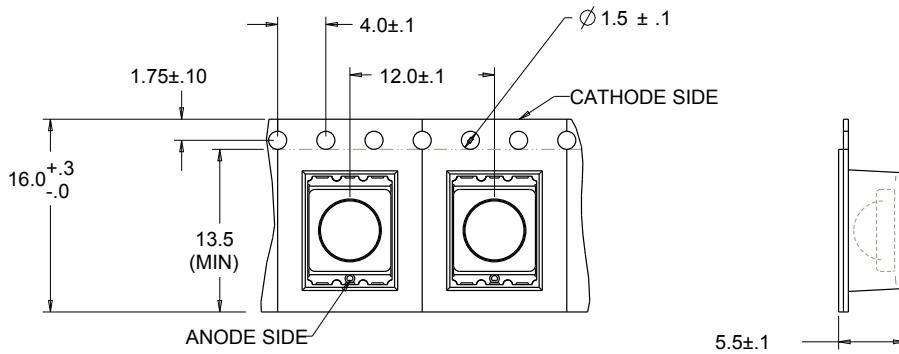
**Recommended solder pad for XLamp XR family LEDs**



**Recommended stencil pattern for XLamp XR family LEDs (hatched area is opening)**

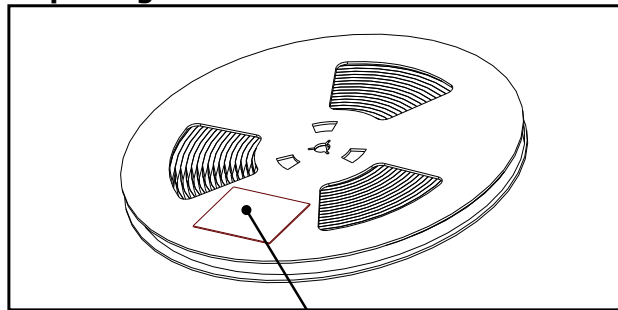
**TAPE AND REEL**

All Cree carrier tapes conform to EIA-481D, Automated Component Handling Systems Standard.  
All dimensions in mm.



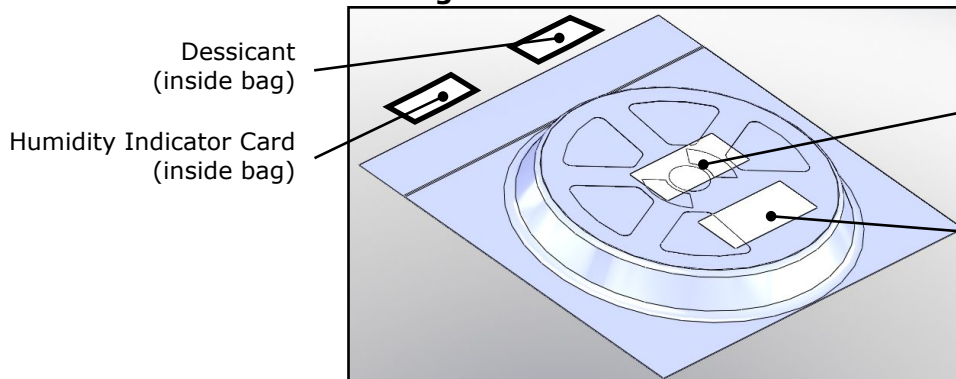
**PACKAGING**

**Unpackaged Reel**



Label with Cree Bin Code,  
Quantity, Reel ID

**Packaged Reel**



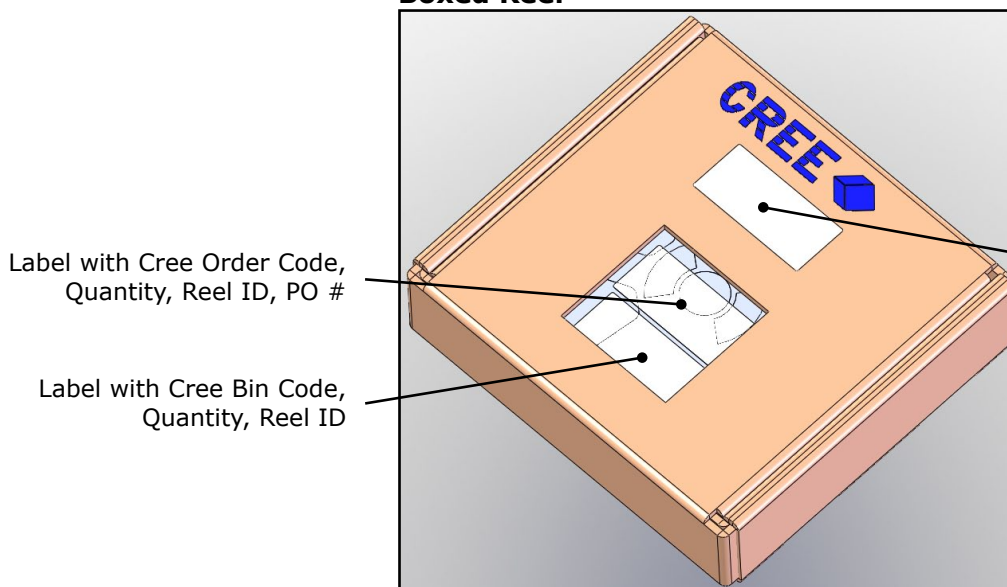
Dessicant  
(inside bag)

Humidity Indicator Card  
(inside bag)

Label with Cree Order Code,  
Quantity, Reel ID, PO #

Label with Cree Bin Code,  
Quantity, Reel ID

**Boxed Reel**



Label with Cree Order Code,  
Quantity, Reel ID, PO #

Label with Cree Bin Code,  
Quantity, Reel ID

Patent Label